TJA1462

CAN FD signal improvement transceiver with Standby mode

Rev. 3.0 — 12 February 2025 Product data sheet

1 General description

The TJA1462 is a member of the TJA146x family of transceivers that provide an interface between a Controller Area Network (CAN) or CAN FD (Flexible Data rate) protocol controller and the physical two-wire CAN bus. TJA146x transceivers implement the CAN physical layer as defined in ISO 11898-2:2024 third edition and SAE J2284-1 to SAE J2284-5, and are fully interoperable with high-speed Classical CAN and CAN FD transceivers.

The TJA1462 includes CAN signal improvement capability (SIC), as defined in ISO 11898-2:2024 parameter set C. CAN signal improvement significantly reduces signal ringing in a network, allowing reliable CAN FD communication to function in larger topologies. In addition, the TJA1462 features a much tighter bit timing symmetry performance to enable CAN FD communication up to 8 Mbit/s.

The TJA1462 is intended as a simple replacement for high-speed Classical CAN and CAN FD transceivers, such as the TJA1042 or TJA1044 from NXP. It offers pin compatibility and is designed to avoid changes to hardware and software design, allowing the TJA1462 to be easily retrofitted to existing applications.

An AEC-Q100 Grade 0 variant, the TJR1462, is available for high temperature applications, supporting operation at 150 °C ambient temperature.

1.1 TJA1462 variants

The TJA1462 comes in two variants, each available in an SO8 or HVSON8 package:

- The TJA1462A is a high-speed CAN transceiver with Normal and Standby modes and a VIO supply pin. The VIO pin allows for direct interfacing with 3.3 V- and 5 V-supplied microcontrollers.
- The TJA1462B is a high-speed CAN transceiver with Normal and Standby modes.

2 Features and benefits

2.1 General

- ISO 11898-2:2024 parameter set A-C, SAE J2284-1 to SAE J2284-5 and SAE J1939-14 compliant
- Implements CAN Signal Improvement Capability as defined in ISO 11898-2:2024 parameter set C to significantly reduce signal ringing effects in a network
- Tighter bit timing symmetry performance versus standard CAN FD transceivers allowing for data rates up to 8 Mbit/s
- Low Electromagnetic Emission (EME) and high Electromagnetic Immunity (EMI)
- Qualified according to AEC-Q100 Grade 1
- TJA1462A only: VIO input for interfacing with 3.3 V to 5 V microcontrollers
- All variants are available in SO8 and leadless HVSON8 (3.0 mm x 3.0 mm) packages; HVSON8 with improved Automated Optical Inspection (AOI) capability.
- Dark green product (halogen free and Restriction of Hazardous Substances (RoHS) compliant)

2.2 Predictable and fail-safe behavior

- Undervoltage detection with defined handling on all supply pins

- Full functionality guaranteed from the undervoltage detection thresholds up to the maximum limiting voltage values
- Defined behavior below the undervoltage detection thresholds
- Transceiver disengages from the bus (high-ohmic) when the supply voltage drops below the Off mode threshold
- Internal biasing of TXD and mode selection input pins, to enable defined fail-safe behavior

2.3 Low-power management

- Very low-current Standby mode with bus (CANH/CANL pins) and host (STB pins) wake-up capability
- TJA1462A only: CAN wake-up receiver powered by V_{IO} allowing V_{CC} to be shut down
- CAN wake-up pattern filter time of 0.5 µs to 1.8 µs, meeting Classical CAN and CAN FD requirements

2.4 Protection

- High ESD handling capability on the bus pins
- Bus pins protected against transients in automotive environments
- Transmit Data (TXD) dominant time-out function
- Thermally protected

3 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage	operating range	4.5	-	5.5	V
I_{CC}	supply current	Normal mode, dominant	-	42	70	mA
		Normal mode, recessive	-	7	10	mA
		Standby mode; TJA1462A	-	-	2	µA
		Standby mode; TJA1462B	-	8	21	µA
$V_{uvd(stb)(VCC)}$	standby undervoltage detection voltage on pin VCC		4	-	4.5	V
$V_{uvhys(stb)(VCC)}$	standby undervoltage hysteresis voltage on pin VCC		50	-	-	mV
$V_{uvd(swoff)(VCC)}$	switch-off undervoltage detection voltage on pin VCC	TJA1462B	2.65	-	2.95	V
V_{IO}	supply voltage on pin VIO		2.95	-	5.5	V
I_{IO}	supply current on pin VIO	Normal mode, dominant; V_{TXD} = 0 V	-	250	760	µA
		Normal mode, recessive; V_{TXD} = V_{IO}	-	150	460	µA
		Standby mode	-	8	19	µA
$V_{uvd(swoff)(VIO)}$	switch-off undervoltage detection voltage on pin VIO		2.65	-	2.95	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2 on pins CANH and CANL	-6	-	+6	kV
V_{CANH}	voltage on pin CANH	limiting value according to IEC 60134	-36	-	+40	V
V_{CANL}	voltage on pin CANL	limiting value according to IEC 60134	-36	-	+40	V
T_{vj}	virtual junction temperature		-40	-	+150	°C

4 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
TJA1462AT	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1
TJA1462BT			
TJA1462ATK	HVSON8	plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 × 3 × 0.85 mm	SOT782-1
TJA1462BTK			

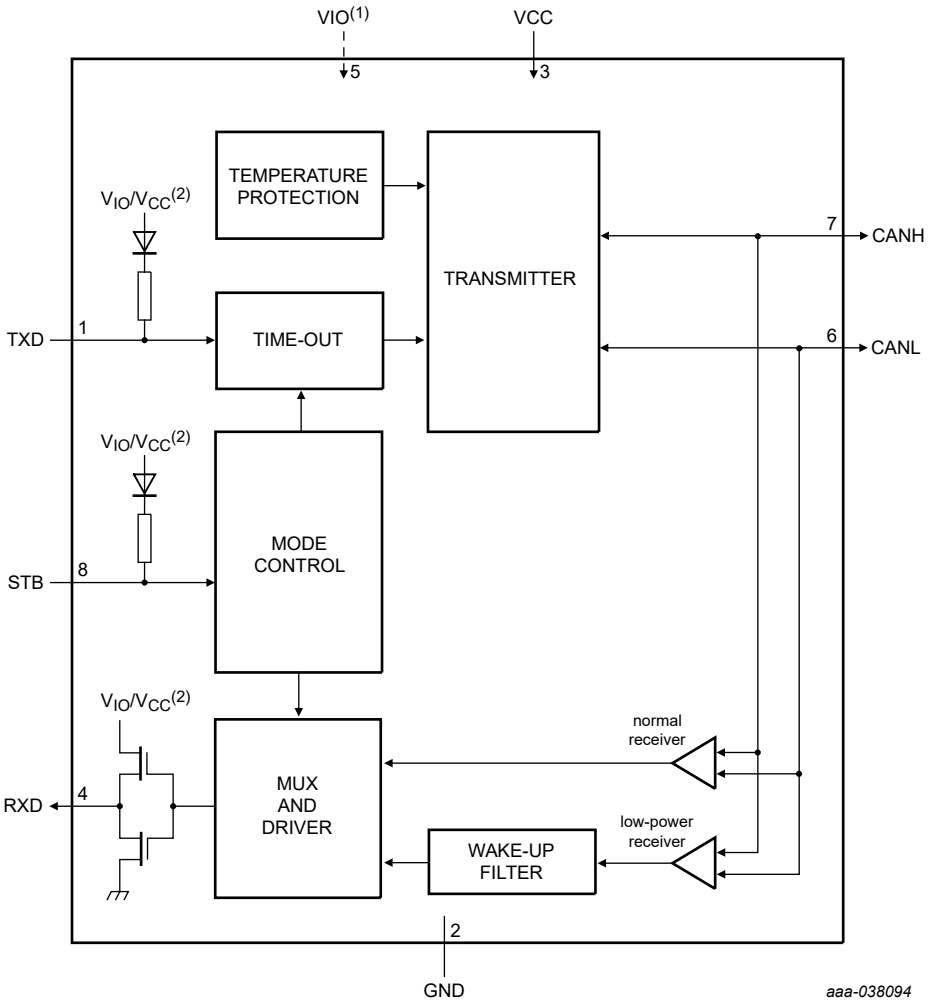
Table 3. TJA1462 feature overview

See Section 18 for a feature overview of the complete TJx14(41/42/43/48)x, TJx14(62/63)x , TJF1441 family.

Device[1]	Modes					Supplies			Data rate		Additional features					
	Normal	Standby	Sleep	Silent/Listen-only	Selectable Off	VCC pin	VIO pin	VBAT pin	Up to 5 Mbit/s CAN FD	Up to 8 Mbit/s CAN FD	Signal improvement[2]	Wake-up source recognition[3]	Short WUP support [0.5 - 1.8 µs][4]	Single supply pin wake-up[5]	TXD dominant time-out	Local diagnostics via ERR_N pin
TJA1462A	●	●				●	●		●	●	●		●	●	●	
TJA1462B	●	●				●			●	●	●		●		●	

[1] TJA1462 is AEC-Q100 Grade 1.
[2] CAN FD Signal Improvement Capability (SIC) according to ISO 11898-2:2024 parameter set C.
[3] RXD is held LOW after wake-up request, enabling wake-up source recognition.
[4] WUP = wake-up pattern according to Figure 7 in ISO 11898-2:2024.
[5] Only VIO supply needed for wake-up in TJA1462A.

5 Block diagram



(1) V_{IO} is only available in the TJA1462A (pin 5 is not connected in the TJA1462B).
(2) V_{IO} in TJA1462A; V_{CC} in TJA1462B.

Figure 1. Block diagram

6 Pinning information

6.1 Pinning

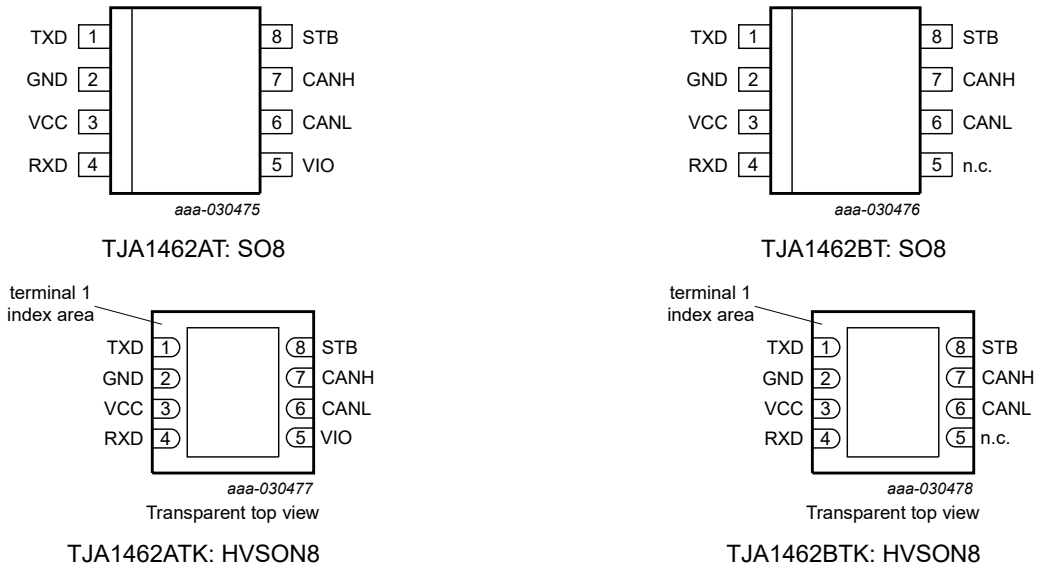


Figure 2. Pin configuration diagrams

6.2 Pin description

Table 4. Pin description

Symbol	Pin	Type[1]	Description
TXD	1	I	transmit data input; inputs data (from the CAN controller) to be written to the bus lines
GND[2]	2	G	ground
VCC	3	P	5 V supply voltage input
RXD	4	O	receive data output; outputs data read from the bus lines (to the CAN controller)
VIO	5	P	supply voltage input for I/O level adapter in TJA1462A
n.c.		-	not connected in TJA1462B
CANL	6	AIO	LOW-level CAN bus line
CANH	7	AIO	HIGH-level CAN bus line
STB	8	I	Standby mode control input; active-HIGH

[1] I: digital input; O: digital output; AIO: analog input/output; P: power supply; G: ground.
[2] HVSON package die supply ground is connected to both the GND pin and the exposed center pad. The GND pin must be soldered to board ground. For enhanced thermal and electrical performance, it is also recommended to solder the exposed center pad to board ground.

7 Functional description

7.1 Operating modes

The TJA1462 supports three operating modes, Normal, Standby and Off. The operating mode is selected via pin STB. See Table 5 for a description of the operating modes under normal supply conditions. Mode changes are completed after transition time $t_{t(moch)}$.

Table 5. Operating modes

Mode	Inputs		Outputs	
	Pin STB	Pin TXD	CAN driver	Pin RXD
Normal	LOW	LOW	dominant	LOW
		HIGH	recessive	LOW when bus dominant
				HIGH when bus recessive
Standby	HIGH	X	biased to ground	follows BUS when wake-up detected
				HIGH when no wake-up detected
Off[1]	X	X	high-ohmic state	high-ohmic state

[1] Off mode is entered when the voltage on pin VIO (TJA1462A) or pin VCC (TJA1462B) is below the switch-off undervoltage detection threshold.

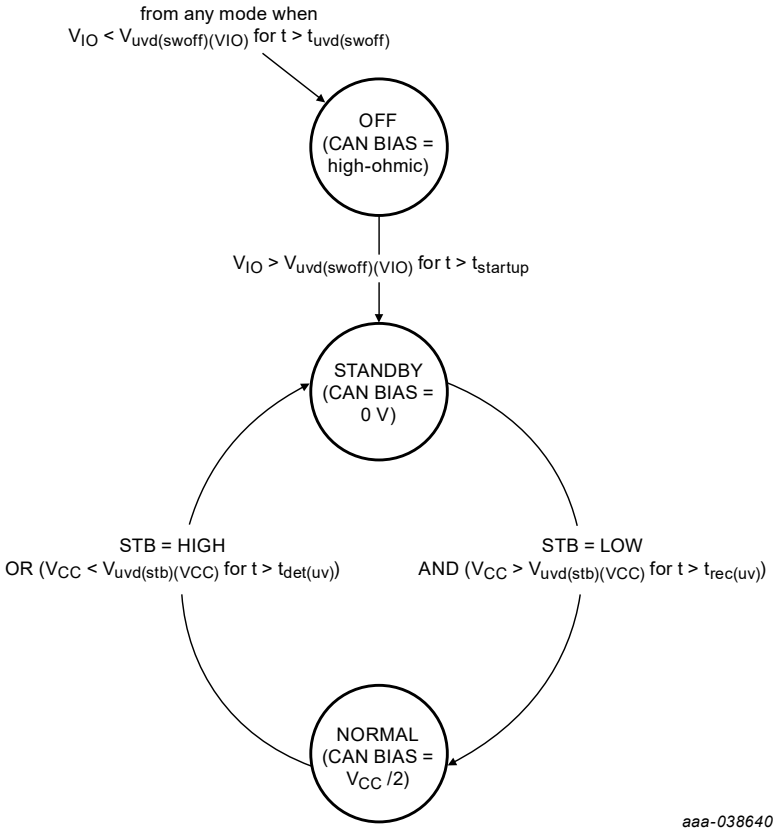


Figure 3. TJA1462A state diagram

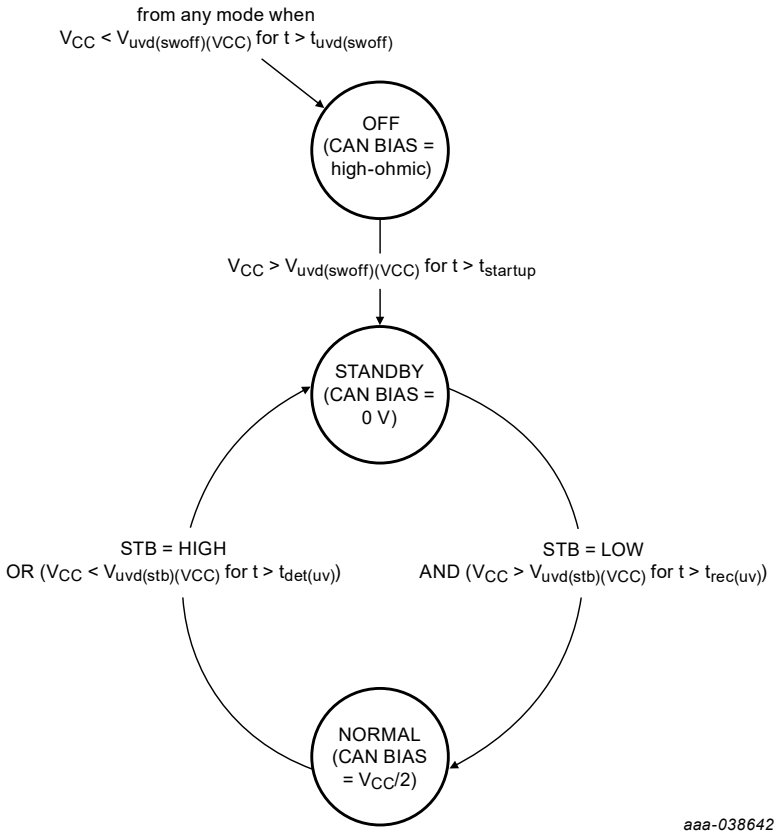


Figure 4. TJA1462B state diagram

7.1.1 Off mode

The TJA1462 switches to Off mode from any mode when the supply voltage (on pin VIO in the TJA1462A and VCC in the TJA1462B) falls below the switch-off undervoltage threshold ($V_{uvd(swoff)(VCC)}$ or $V_{uvd(swoff)(VIO)}$). This is the default mode when the supply is first connected.

In Off mode, the CAN pins and pin RXD are in a high-ohmic state.

7.1.2 Standby mode

When the supply voltage (V_{IO} for TJA1462A or V_{CC} for TJA1462B) rises above the switch-off undervoltage detection threshold, the TJA1462 starts to boot up, triggering an initialization procedure. The TJA1462 switches to the selected mode after $t_{startup}$.

Standby mode is selected when pin STB goes HIGH. In this mode, the transceiver is unable to transmit or receive data and a low-power receiver is activated to monitor the bus for a wake-up pattern. The transmitter and Normal-mode receiver blocks are switched off and the bus pins are biased to ground to minimize system supply current. Pin RXD follows the bus after a wake-up request has been detected.

A transition to Normal mode is triggered when STB is forced LOW (provided $V_{CC} > V_{uvd(stb)(VCC)}$ and $V_{IO} > V_{uvd(swoff)(VIO)}$ in the TJA1462A).

If V_{CC} is below $V_{uvd(stb)(VCC)}$ when STB goes LOW (with $V_{IO} > V_{uvd(swoff)(VIO)}$ in TJA1462A and $V_{CC} > V_{uvd(swoff)(VCC)}$ in TJA1462B), the TJA1462 will remain in Standby mode forwarding the converted differential data on the bus pins via the low-power receiver to pin RXD.

In the TJA1462A, the low-power receiver is supplied from V_{IO} and can detect CAN bus activity when V_{IO} is above $V_{uvd(swoff)(VIO)}$ (even if V_{IO} is the only available supply voltage).

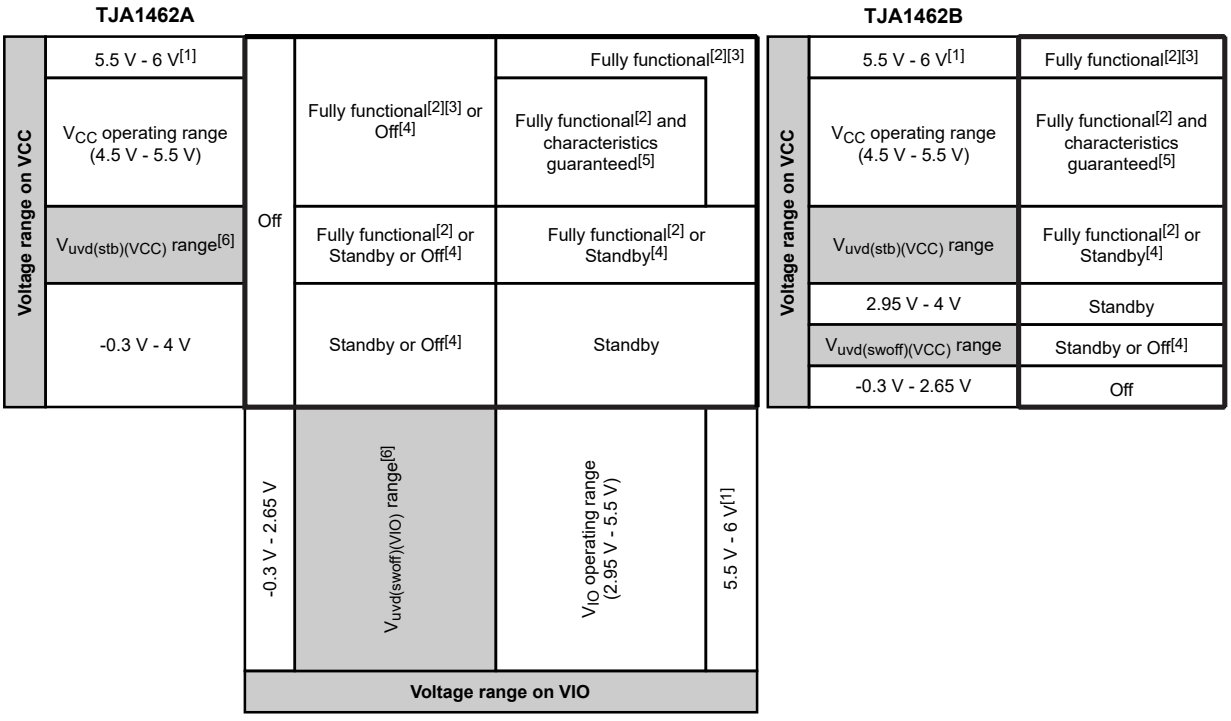
7.1.3 Normal mode

A LOW level on pin STB selects Normal mode, provided the supply voltage on pin VCC is above the standby undervoltage detection threshold ($V_{uvd(stb)(VCC)}$). Additionally, for the TJA1462A variant, V_{IO} must be above the switch-off undervoltage detection threshold $V_{uvd(swoff)VIO}$.

In this mode, the transceiver can transmit and receive data via bus lines CANH and CANL. Pin TXD must be HIGH at least once in Normal Mode before transmission can begin. The differential receiver converts the analog data on the bus lines into digital data on pin RXD. The slopes of the output signals on the bus lines are controlled internally and are optimized in a way that guarantees the lowest possible EME. In order to support high bit rates, especially in CAN FD systems, the Signal Improvement function largely eliminates topology-related reflections and impedance mismatches. In recessive state, the output voltage on the bus pins is $V_{CC}/2$.

7.1.4 Operating modes and gap-free operation

Gap-free operation guarantees defined behavior at all voltage levels. Supply voltage-to-operating mode mapping is detailed in Figure 5 and in the state diagrams (Figure 3 and Figure 4).



[1] 6 V is the IEC 60134 Absolute Maximum Rating (AMR) for VCC and VIO (see Limiting values table). Above the AMR, irreversible changes in characteristics, functionality or performance may occur. Returning from above AMR to the operating range, datasheet characteristics and functionality cannot be guaranteed.
[2] Target transceiver functionality as described in this datasheet is applicable.
[3] Prolonged operation of the device outside the operating range may impact reliability over lifetime. Returning to the operating range, datasheet characteristics are guaranteed provided the AMR has not been exceeded.
[4] For a given value of V_{CC} (and V_{IO} in TJA1462A), a specific device will be in a single defined state determined by its undervoltage detection thresholds ($V_{uvd(stb)(VCC)}$, $V_{uvd(swoff)(VIO)}$ and $V_{uvd(swoff)(VCC)}$). The actual thresholds can vary between devices (within the ranges specified in this data sheet). To guarantee the device will be in a specific state, V_{IO} and V_{CC} must be either above the maximum or below the minimum thresholds specified for these undervoltage detection ranges.
[5] Datasheet characteristics are guaranteed within the V_{CC} and V_{IO} operating ranges. Exceptions are described in the Static and Dynamic characteristics tables.
[6] The following applies to TJA1462A:
- If both V_{CC} and V_{IO} are above the undervoltage threshold, the device is fully functional.
- If V_{CC} is below and V_{IO} above the undervoltage threshold, the device is in Standby mode.
- If V_{IO} is below the undervoltage threshold, the device is in Off mode, regardless of V_{CC}.

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Figure 5. Supply voltage ranges and gap-free operation

7.2 Remote wake-up (via the CAN bus)

The TJA1462 wakes up from Standby mode when a dedicated wake-up pattern (according to Figure 7 in ISO 11898-2: 2024) is detected on the bus.

The wake-up pattern consists of:

- a dominant phase of at least $t_{wake(busdom)}$ followed by
- a recessive phase of at least $t_{wake(busrec)}$ followed by
- a dominant phase of at least $t_{wake(busdom)}$

Dominant or recessive bits between the above mentioned phases that are shorter than $t_{wake(busdom)}$ and $t_{wake(busrec)}$ respectively are ignored.

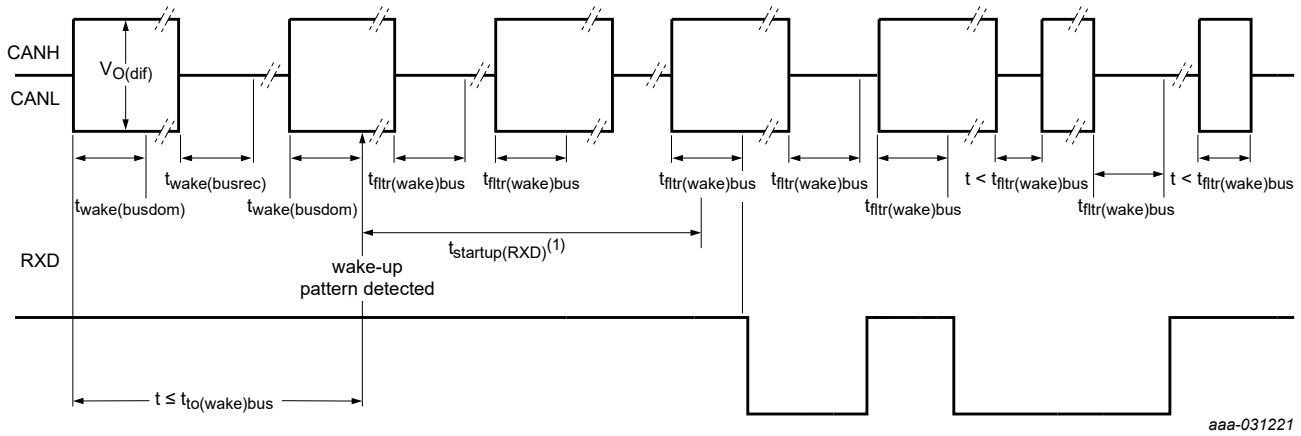
The complete dominant-recessive-dominant pattern must be received within $t_{to(wake)bus}$ to be recognized as a valid wake-up pattern (see Figure 6). Otherwise, the internal wake-up logic is reset. The complete wake-up

pattern then needs to be retransmitted to trigger a wake-up event. Pin RXD remains HIGH until the wake-up event has been triggered.

After a wake-up sequence has been detected, the TJA1462 remains in Standby mode with the bus signals reflected on RXD after $t_{startup(RXD)}$. Note that dominant or recessive phases lasting less than $t_{fltr(wake)bus}$ will not be detected by the low-power differential receiver and will not be reflected on RXD in Standby mode.

A wake-up event is not flagged on RXD if any of the following events occurs while a valid wake-up pattern is being received:

- The device switches to Normal mode
- The complete wake-up pattern was not received within $t_{to(wake)bus}$
- A V_{CC} or V_{IO} switch-off undervoltage is detected ($V_{CC} < V_{uvd(swoff)(VCC)}$ or $V_{IO} < V_{uvd(swoff)(VIO)}$; see Section 7.3.3)



(1) During $t_{startup(RXD)}$, the low-power receiver is on but pin RXD is not active (i.e. HIGH/recessive). The first dominant pulse of width ≥ $t_{fltr(wake)bus}$ that ends after $t_{startup(RXD)}$ will trigger RXD to go LOW/dominant.

Figure 6. Wake-up timing

7.3 Fail-safe features

7.3.1 TXD dominant time-out function

A 'TXD dominant time-out' timer is started when pin TXD is set LOW. If the LOW state on this pin persists for longer than $t_{to(dom)TXD}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when pin TXD goes HIGH.

7.3.2 Internal biasing of TXD and STB input pins

Pins TXD and STB have internal pull-ups to V_{CC}/V_{IO} to ensure a safe, defined state in case one, or both, of these pins is left or becomes floating. Pull-up resistors are active on these pins in all states; they should be held at the V_{CC}/V_{IO} level in Standby mode to minimize supply current.

7.3.3 Undervoltage detection on pins VCC and VIO

If V_{CC} drops below the standby undervoltage detection threshold ($V_{uvd(stb)(VCC)}$) for $t_{det(uv)}$, the transceiver switches to Standby mode. The logic state of pin STB is ignored until V_{CC} has recovered.

In the TJA1462A, if V_{IO} drops below the switch-off undervoltage detection threshold ($V_{uvd(swoff)(VIO)}$) for $t_{uvd(swoff)}$, the transceiver switches to Off mode and disengages from the bus (high-ohmic) until V_{IO} has recovered.

In the TJA1462B, if V_{CC} drops below the switch-off undervoltage detection threshold ($V_{uvd(swoff)(VCC)}$) for $t_{uvd(swoff)}$, the transceiver switches to Off mode and disengages from the bus (high-ohmic) until V_{CC} has recovered.

7.3.4 Overtemperature protection

The device is protected against overtemperature conditions. If the junction temperature exceeds the shutdown junction temperature, $T_{j(sd)}$, the CAN bus drivers are disabled. When the junction temperature drops below $T_{j(sd)rel}$, the CAN bus drivers recover once TXD has been reset to HIGH and Normal mode is selected.

7.3.5 I/O levels

Pin VIO on the TJA1462A should be connected to the microcontroller supply voltage (see Figure 10). This adjusts the signal levels on pins TXD, RXD and STB to the I/O levels of the microcontroller, allowing for direct interfacing without additional glue logic. Pin VIO also provides the internal supply voltage for the low-power differential receiver. For applications running in low-power mode, this allows the bus lines to be monitored for activity even if there is no supply voltage on pin VCC.

All I/O levels are related to V_{CC} in the TJA1462B and are, therefore, compatible with 5 V microcontrollers.

For both the TJA1462A and TJA1462B, spurious signals from the microcontroller on pin STB are filtered out with a filter time of $t_{fltr(IO)}$.

8 Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). All voltages are referenced to GND, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
V_x	voltage on pin x[1]	pins VCC, VIO (TJA1462A), TXD, STB	-0.3	+6	V
			-	+7[2]	V
		pins CANH, CANL	-36	+40	V
		pin RXD			
		TJA1462A	-0.3	V_{IO}+0.3[3]	V
		TJA1462B	-0.3	V_{CC}+0.3[3]	V
$V_{(CANH-CANL)}$	voltage between pin CANH and pin CANL		-40	+40	V
V_{trt}	transient voltage	on pins CANH, CANL [4]			
		pulse 1	-100	-	V
		pulse 2a	-	+75	V
		pulse 3a	-150	-	V
		pulse 3b	-	+100	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2 (150 pF, 330 Ω discharge circuit) [5]			
		on pins CANH, CANL	-6	+6	kV
		SAE J2962-2:2019 (330 pF, 2kΩ) on pins CANH, CANL [6]			
		powered air discharge	-15	+15	kV
		powered contact discharge	-8	+8	kV
		Human Body Model (HBM)			
		on any pin [7]	-4	+4	kV
		on pins CANH, CANL [8]	-8	+8	kV
		Charged Device Model (CDM) [9]			
		on corner pins	-750	+750	V
		on any other pin	-500	+500	V
T_{vj}	virtual junction temperature	[10]	-40	+150	°C
T_{stg}	storage temperature	[11]	-55	+150	°C

[1] The device can sustain voltages up to the specified values over the product lifetime, provided applied voltages (including transients) never exceed these values.
[2] The device can withstand voltages between 6 V and 7 V for a total of 20 s over the product lifetime.
[3] Subject to the qualifications detailed in Table notes 1 and 2 above for pins VCC, VIO, TXD and STB.
[4] Verified by an external test house according to IEC TS 62228, Section 4.2.4; parameters for standard pulses defined in ISO7637.
[5] Verified by an external test house according to IEC TS 62228, Section 4.3.
[6] Verified by an external test house according to ISO 10605.
[7] According to AEC-Q100-002.
[8] Pins stressed to reference group containing all ground and supply pins, emulating the application circuits (Figure 10 and Figure 11). HBM pulse as specified in AEC-Q100-002 used.
[9] According to AEC-Q100-011.

[10] In accordance with IEC 60747-1. An alternative definition of virtual junction temperature is: $T_{vj} = T_{amb} + P \times R_{th(j-a)}$, where $R_{th(j-a)}$ is a fixed value used in the calculation of T_{vj}. The rating for T_{vj} limits the allowable combinations of power dissipation (P) and ambient temperature (T_{amb}).

[11] T_{stg} in application according to IEC61360-4. For component transport and storage conditions, see instead IEC61760-2.

9 Thermal characteristics

Table 7. Thermal characteristics

Value determined for free convection conditions on a JEDEC 2S2P board.

Symbol	Parameter	Conditions[1]	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	SO8	100	K/W
		HVSON8	60	K/W
$R_{th(j-c)}$	thermal resistance from junction to case[2]	HVSON8	22	K/W
Ψ_{j-top}	thermal characterization parameter from junction to top of package	SO8	17	K/W
		HVSON8	16	K/W

[1] According to JEDEC JESD51-2, JESD51-5 and JESD51-7 at natural convection on 2s2p board. Board with two inner copper layers (thickness: 35 µm) and thermal via array under the exposed pad connected to the first inner copper layer (thickness: 70 µm).

[2] Case temperature refers to the center of the heatsink at the bottom of the package.

10 Static characteristics

Table 8. Static characteristics

T_{vj} = -40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground; positive currents flow into the IC.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply; pin VCC						
V_{CC}	supply voltage		4.5	-	5.5	V
$V_{uvd(stb)}$	standby undervoltage detection voltage	[2]	4	-	4.5	V
$V_{uvhys(stb)}$	standby undervoltage hysteresis voltage		50	-	-	mV
$V_{uvd(swoff)}$	switch-off undervoltage detection voltage	TJA1462B [2]	2.65	-	2.95	V
I_{CC}	supply current	Normal mode				
		dominant; V_{TXD} = 0 V; t < $t_{to(dom)TXD}$	-	42	70	mA
		V_{TXD} = 0 V; short circuit on bus lines; -3 V < (V_{CANH} = V_{CANL}) < +40 V	-	-	125	mA
		recessive; V_{TXD} = V_{IO}[3]	-	7	10	mA
		Standby mode				
		TJA1462A; T_{vj} < 85 °C	-	-	2	µA
		TJA1462B; T_{vj} < 85 °C	-	8	21	µA
I/O level adapter supply; pin VIO (TJA1462A)						
V_{IO}	supply voltage		2.95	-	5.5	V
$V_{uvd(swoff)}$	switch-off undervoltage detection voltage	[2]	2.65	-	2.95	V

Table 8. Static characteristics...*continued*

T_{vj} = -40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground; positive currents flow into the IC.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{IO}	supply current	Normal mode, dominant; V_{TXD} = 0 V	-	250	760	µA
		Normal mode, recessive; V_{TXD} = V_{IO}	-	150	460	µA
		Standby mode; T_{vj} < 85 °C	-	8	19	µA
CAN transmit data input; pin TXD						
V_{IH}	HIGH-level input voltage		$0.7V_{IO}$[3]	-	-	V
V_{IL}	LOW-level input voltage		-	-	$0.3V_{IO}$[3]	V
$V_{hys(TXD)}$	hysteresis voltage on pin TXD		50	-	-	mV
R_{pu}	pull-up resistance		20	-	80	kΩ
C_i	input capacitance	[4]	-	-	10	pF
CAN receive data output; pin RXD						
I_{OH}	HIGH-level output current	V_{RXD} = V_{IO}[3] - 0.4 V	-10	-	-1	mA
I_{OL}	LOW-level output current	V_{RXD} = 0.4 V; bus dominant	1	-	10	mA
Standby control input; pin STB						
V_{IH}	HIGH-level input voltage		$0.7V_{IO}$[3]	-	-	V
V_{IL}	LOW-level input voltage		-	-	$0.3V_{IO}$[3]	V
V_{hys}	hysteresis voltage		50	-	-	mV
R_{pu}	pull-up resistance		20	-	80	kΩ
C_i	input capacitance	[4]	-	-	10	pF
Bus lines; pins CANH and CANL						
$V_{O(dom)}$	dominant output voltage	V_{TXD} = 0 V; t < $t_{to(dom)TXD}$; V_{CC} = 4.75 V to 5.25 V				
		pin CANH; R_L = 50 Ω to 65 Ω	2.89	3.5	4.26	V
		pin CANL; R_L = 50 Ω to 65 Ω	0.77	1.5	2.13	V
V_{TXsym}	transmitter voltage symmetry	V_{TXsym} = V_{CANH} + V_{CANL}; C_{SPLIT} = 4.7 nF; f_{TXD} = 250 kHz, 1 MHz or 2.5 MHz [4] [5]	$0.9V_{CC}$	-	$1.1V_{CC}$	V
$V_{cm(step)}$	common mode voltage step	[4] [5] [6]	-150	-	+150	mV
$V_{cm(p-p)}$	peak-to-peak common mode voltage	[4] [5] [6]	-300	-	+300	mV
$V_{O(dif)}$	differential output voltage	dominant; Normal mode; V_{TXD} = 0 V; t < $t_{to(dom)TXD}$; V_{CC} = 4.75 V to 5.25 V				
		R_L = 50 Ω to 65 Ω	1.5	-	2.75	V
		R_L = 45 Ω to 70 Ω	1.4	-	3.3	V
		R_L = 2240 Ω [4]	1.5	-	5	V

Table 8. Static characteristics...*continued*

T_{vj} = -40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground; positive currents flow into the IC.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		recessive; no load				
		Normal mode; $V_{TXD} = V_{IO}$[3]	-50	-	+50	mV
		Standby mode	-0.2	-	+0.2	V
$V_{O(rec)}$	recessive output voltage	Normal mode; $V_{TXD} = V_{IO}$[3]; no load	2	2.5	3	V
		Standby mode; no load	-0.1	-	+0.1	V
$V_{th(RX)dif}$	differential receiver threshold voltage	-12 V ≤ V_{CANH} ≤ +12 V; -12 V ≤ V_{CANL} ≤ +12 V				
		Normal mode	0.5	-	0.9	V
		Standby mode	0.4	-	1.1	V
$V_{rec(RX)}$	receiver recessive voltage	-12 V ≤ V_{CANH} ≤ +12 V; -12 V ≤ V_{CANL} ≤ +12 V				
		Normal mode	-8	-	+0.5	V
		Standby mode	-8	-	+0.4	V
$V_{dom(RX)}$	receiver dominant voltage	-12 V ≤ V_{CANH} ≤ +12 V; -12 V ≤ V_{CANL} ≤ +12 V				
		Normal mode	0.9	-	9	V
		Standby mode	1.1	-	9	V
$V_{hys(RX)dif}$	differential receiver hysteresis voltage	-12 V ≤ V_{CANH} ≤ +12 V; -12 V ≤ V_{CANL} ≤ +12 V; Normal mode	100	-	-	mV
$I_{O(sc)}$	short-circuit output current	-15 V ≤ V_{CANH} ≤ +40 V; -15 V ≤ V_{CANL} ≤ +40 V	-	-	115	mA
$I_{O(sc)rec}$	recessive short-circuit output current	-27 V ≤ V_{CANH} ≤ +32 V; -27 V ≤ V_{CANL} ≤ +32 V; Normal mode; $V_{TXD} = V_{IO}$[3] for t > t > $t_{d(TXD-buspasrec)start}$[7]	-3	-	+3	mA
I_L	leakage current	$V_{CC} = V_{IO}$ = 0 V or pins shorted to GND via 47 kΩ; $V_{CANH} = V_{CANL}$ = 5 V	-10	-	+10	µA
R_i	input resistance	-2 V ≤ V_{CANL} ≤ +7 V; -2 V ≤ V_{CANH} ≤ +7 V; passive recessive[8]	25	40	50	kΩ
ΔR_i	input resistance deviation	0 V ≤ V_{CANL} ≤ +5 V; 0 V ≤ V_{CANH} ≤ +5 V; passive recessive[8]	-3	-	+3	%
$R_{i(dif)}$	differential input resistance	-2 V ≤ V_{CANL} ≤ +7 V; -2 V ≤ V_{CANH} ≤ +7 V; passive recessive[8]	50	80	100	kΩ
$C_{i(cm)}$	common-mode input capacitance	[4]	-	-	30	pF
$C_{i(dif)}$	differential input capacitance	[4]	-	-	15	pF
Signal Improvement function on CANH or CANL; +4.75 V ≤ V_{CC} ≤ +5.25 V; see Figure 9						
$R_{i(dom)}$	dominant phase input resistance	bus dominant; V_{CC} - 1.6 V ≤ V_{CANH} ≤ V_{CC} - 1.2 V; +1.2 V ≤ V_{CANL} ≤ +1.6 V;	-	-	30	Ω

Table 8. Static characteristics...*continued*

T_{vj} = -40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground; positive currents flow into the IC.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{i(dif)dom}$	dominant phase differential input resistance	$R_{i(dif)dom} = R_{i(dom)CANH} + R_{i(dom)CANL}$	-	-	60	Ω
$R_{i(actrec)}$	active recessive phase input resistance[9]	bus dominant-to-recessive transition [10] +1.5 V ≤ V_{CANH} ≤ V_{CC} - 1.5 V; +1.5 V ≤ V_{CANL} ≤ V_{CC} - 1.5 V; $R_{i(dif)actrec} = R_{i(actrec)CANH} + R_{i(actrec)CANL}$	37.5	-	62.5	Ω
$R_{i(dif)actrec}$	active recessive phase differential input resistance[9]		75	-	125	Ω
Temperature detection						
$T_{j(sd)}$	shutdown junction temperature	[4]	180	-	200	°C
$T_{j(sd)rel}$	release shutdown junction temperature	[4]	175	-	195	°C

[1] All parameters are guaranteed over the junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.
[2] Undervoltage is detected between min and max values. Undervoltage is guaranteed to be detected below min value and guaranteed not to be detected above max value.
[3] V_{CC} in TJA1462B
[4] Not tested in production; guaranteed by design.
[5] The test circuit used to measure the bus output voltage symmetry and the common-mode voltages (which includes C_{SPLIT}) is shown in Figure 13.
[6] See Figure 7.
[7] This parameter is defined in ISO 11898-2:2024 parameter set C and is specified in the Dynamic Characteristics table (see Table 9 and Figure 9).
[8] Passive recessive in accordance with ISO 11898-2. Input impedance is passive once the signal improvement phase has come to an end (active recessive end).
[9] Active recessive phases are not DC states and are only valid for a limited time after a dominant-to-recessive transition on pin TXD. The maximum value specified is lower than proscribed in ISO11898-2:2024 parameter set C (a lower value is preferred).
[10] Both conditions and the maximum specified values are tighter, thus better than prescribed in ISO11898-2:2024 parameter set C.

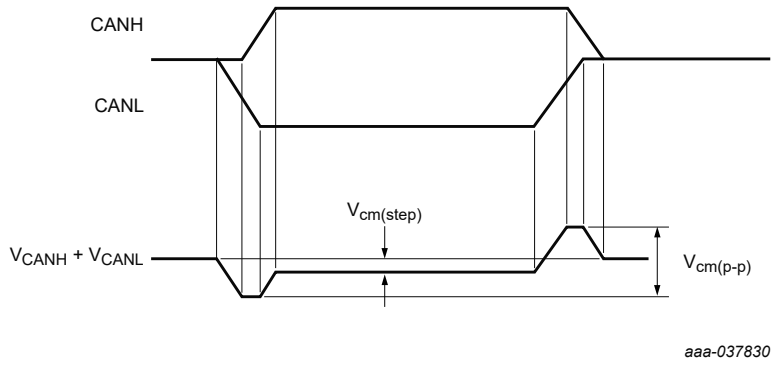


Figure 7. CAN bus common-mode voltage according to SAE 1939-14

11 Dynamic characteristics

Table 9. Dynamic characteristics

T_{vj} = −40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground.[1]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
CAN timing characteristics according to ISO 11898-2:2024; see Figure 8 and Figure 12						
$t_{d(TXDL-RXDL)}$	delay time from TXD LOW to RXD LOW	Normal mode	-	-	255	ns
$t_{d(TXDH-RXDH)}$	delay time from TXD HIGH to RXD HIGH	Normal mode	-	-	255	ns
CAN timing characteristics according to ISO 11898-2:2024; V_{CC} = 4.75 V to 5.25 V; see Figure 8, Figure 9 and Figure 12						
$t_{d(TXD-busdom)}$	delay time from TXD to bus dominant	Normal mode	-	-	80	ns
$t_{d(TXD-busrec)}$	delay time from TXD to bus recessive	Normal mode	-	-	80	ns
$t_{d(busdom-RXD)}$	delay time from bus dominant to RXD	Normal mode	-	-	110	ns
$t_{d(busrec-RXD)}$	delay time from bus recessive to RXD	Normal mode	-	-	110	ns
$t_{d(TXDL-RXDL)}$	delay time from TXD LOW to RXD LOW	Normal mode	-	-	190	ns
$t_{d(TXDH-RXDH)}$	delay time from TXD HIGH to RXD HIGH	Normal mode	-	-	190	ns
$t_{d(TXD-buspasrec)start}$	delay time from TXD to bus passive recessive start	Normal mode [2] [3]	415	-	530	ns
$t_{d(TXD-busactrec)start}$	delay time from TXD to bus active recessive start	Normal mode [2]	70	-	120	ns
$t_{d(TXD-busactrec)end}$	delay time from TXD to bus active recessive end	Normal mode [2]	355	-	480	ns
CAN FD timing characteristics according to ISO 11898-2:2024 parameter set C ($t_{bit(TXD)}$ ≥ 125 ns, up to 8 Mbit/s)[4]; V_{CC} = 4.75 V to 5.25 V; see Figure 8 and Figure 12						
$\Delta t_{bit(bus)}$	transmitted recessive bit width deviation	$\Delta t_{bit(bus)} = t_{bit(bus)} - t_{bit(TXD)}$	-10	-	+10	ns
Δt_{rec}	receiver timing symmetry	$\Delta t_{rec} = t_{bit(RXD)} - t_{bit(bus)}$	-20	-	+15	ns
$\Delta t_{bit(RXD)}$	received recessive bit width deviation	$\Delta t_{bit(RXD)} = t_{bit(RXD)} - t_{bit(TXD)}$	-30	-	+20	ns
CAN FD timing characteristics ($t_{bit(TXD)}$ ≥ 200 ns, up to 5 Mbit/s) [5]; see Figure 8 and Figure 12						
$\Delta t_{bit(bus)}$	transmitted recessive bit width deviation	$\Delta t_{bit(bus)} = t_{bit(bus)} - t_{bit(TXD)}$	-30	-	+30	ns
Δt_{rec}	receiver timing symmetry	$\Delta t_{rec} = t_{bit(RXD)} - t_{bit(bus)}$	-45	-	+15	ns
$\Delta t_{bit(RXD)}$	received recessive bit width deviation	$\Delta t_{bit(RXD)} = t_{bit(RXD)} - t_{bit(TXD)}$	-50	-	+40	ns
Dominant time-out time; pin TXD						
$t_{to(dom)TXD}$	TXD dominant time-out time	V_{TXD} = 0 V; Normal mode [2] [6]	0.8	-	9	ms
Bus wake-up times; pins CANH and CANL; see Figure 6						
$t_{wake(busdom)}$	bus dominant wake-up time	Standby mode [2] [7]	0.5	-	1.8	µs
$t_{wake(busrec)}$	bus recessive wake-up time	Standby mode [2] [7]	0.5	-	1.8	µs
$t_{to(wake)bus}$	bus wake-up time-out time	Standby mode [2] [6]	0.8	-	9	ms
$t_{fltr(wake)bus}$	bus wake-up filter time	Standby mode [2]	-	-	1.8	µs

Table 9. Dynamic characteristics...*continued*

T_{vj} = −40 °C to +150 °C; V_{CC} = 4.5 V to 5.5 V; V_{IO} = 2.95 V to 5.5 V (TJA1462A); R_L = 60 Ω unless specified otherwise; all voltages are defined with respect to ground.[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Mode transitions							
$t_{t(moch)}$	mode change transition time		[2]	-	-	50	µs
$t_{startup}$	start-up time		[2]	-	-	1.5	ms
$t_{startup(RXD)}$	RXD start-up time	after wake-up detected	[2] [8]	4	-	20	µs
IO filter; pin STB							
$t_{filtr(IO)}$	IO filter time		[9]	1	-	5	µs
Undervoltage detection; Figure 3 and Figure 4							
$t_{det(uv)}$	undervoltage detection time	on pin VCC	[2]	-	-	30	µs
$t_{uvd(swoff)}$	switch-off undervoltage detection time	on pin VCC; TJA1462B	[2]	-	-	30	µs
		on pin VIO; TJA1462A	[2]			30	µs
$t_{rec(uv)}$	undervoltage recovery time	on pin VCC	[2]	-	-	50	µs

[1] All parameters are guaranteed over the junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.
[2] Not tested in production; guaranteed by design.
[3] If TXD goes LOW before the recessive transition has been completed, the bus switches to dominant.
[4] Compliance with parameter set C requirements implies compliance for parameter sets A ($t_{bit(TXD)}$ ≥ 500 ns, up to 2 Mbit/s) and B ($t_{bit(TXD)}$ ≥ 200 ns, up to 5 Mbit/s).
[5] For reasons related to CAN FD bit timing symmetry, these values are centered around the nominal bit length. Details can be found in document AH2002 'TJx144x/TJx146x Application Hints', available on request from NXP Semiconductors
[6] Time-out occurs between the min and max values. Time-out is guaranteed not to occur below the min value; time-out is guaranteed to occur above the max value.
[7] A dominant/recessive phase shorter than the min value is guaranteed not be seen as a dominant/recessive bit; a dominant/recessive phase longer than the max value is guaranteed to be seen as a dominant/recessive bit.
[8] When a wake-up is detected, RXD start-up time is between the min and max values. RXD cannot be relied on below the min value; RXD can be relied on above the max value; see Figure 6.
[9] Pulses shorter than the min value are guaranteed to be filtered out; pulses longer than the max value are guaranteed to be processed.

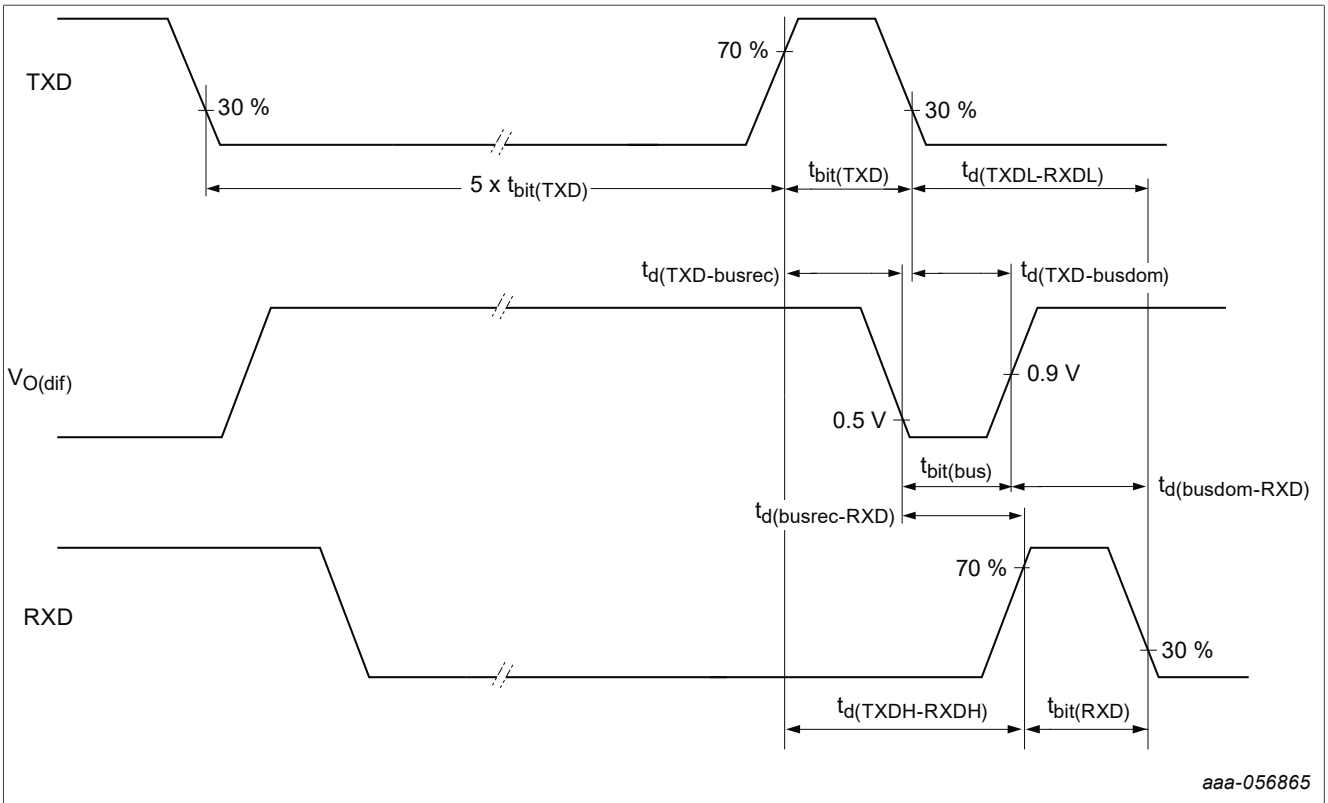
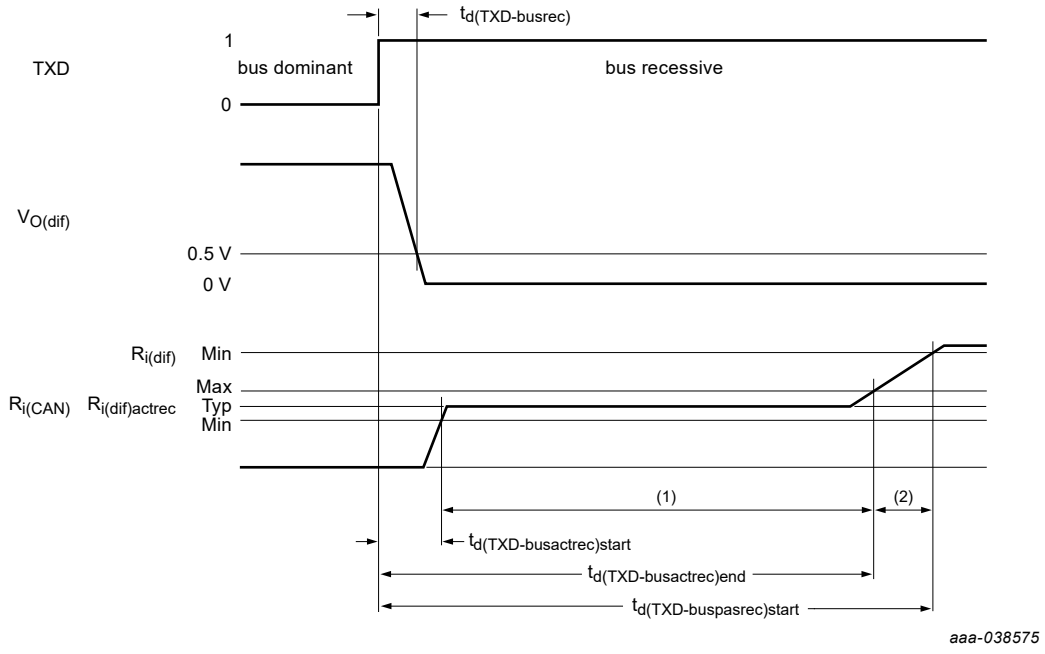


Figure 8. CAN transceiver timing diagram according to ISO 11898-2:2024

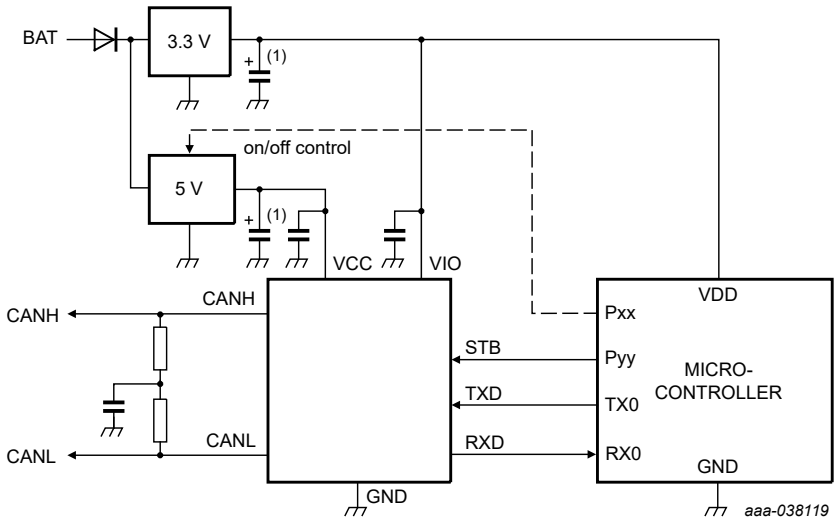


(1) Active recessive phase (2) Release phase.

Figure 9. Transmitter impedance and timing diagram for dominant-to-passive recessive transition according to ISO11898-2:2024 parameter set C.

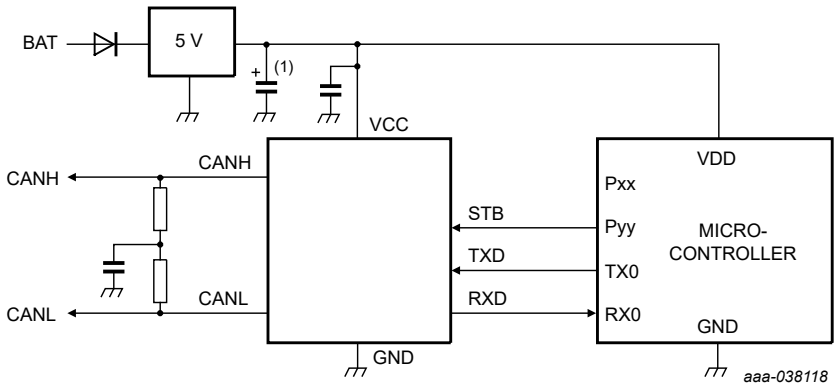
12 Application information

12.1 Application diagrams



(1) Optional, depends on regulator.

Figure 10. Typical TJA1462A application with a 3.3 V microcontroller



(1) Optional, depends on regulator.

Figure 11. Typical TJA1462B application with a 5 V microcontroller

12.2 Application hints

Further information on the application of the TJA1462 can be found in NXP application hints AH2002 *'TJx144x/ TJx146x Application Hints'*, available on request from NXP Semiconductors.

13 Test information

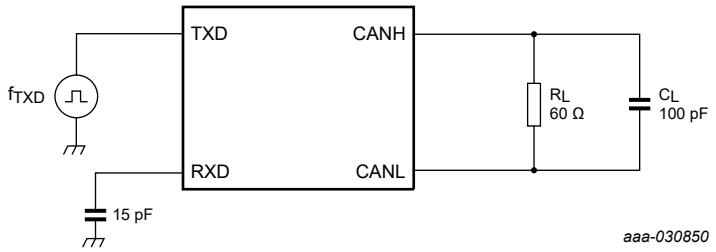


Figure 12. CAN transceiver timing test circuit

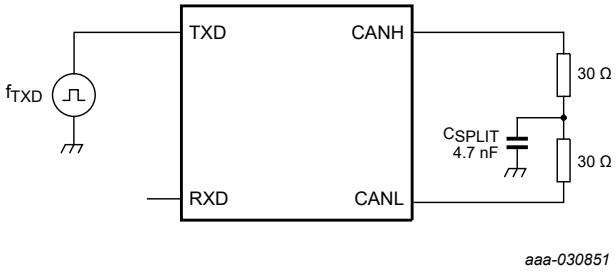


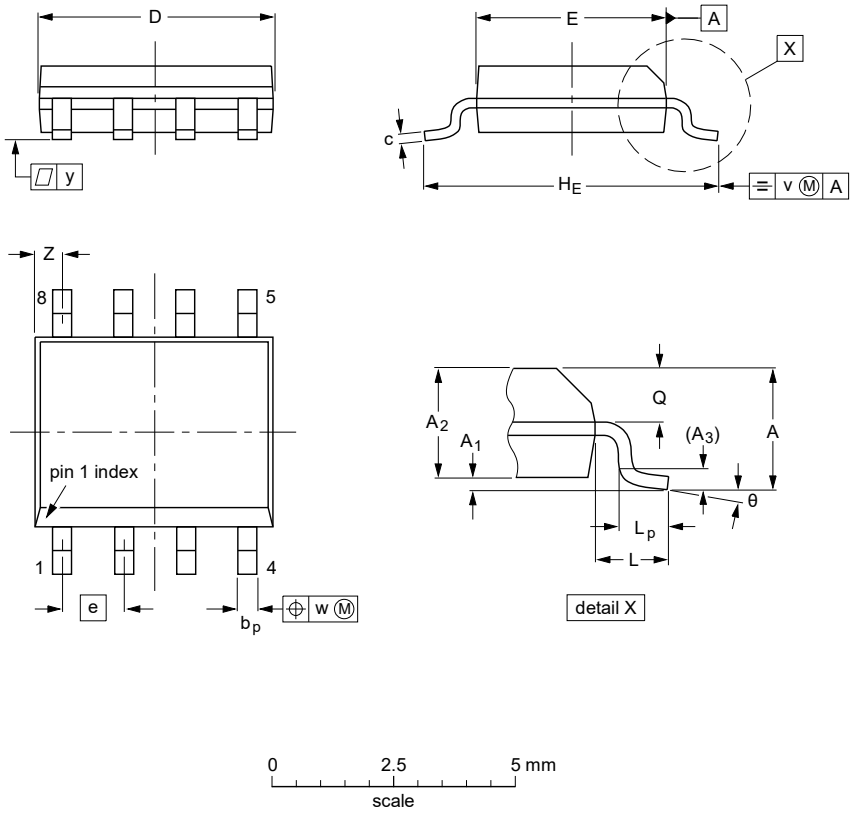
Figure 13. Test circuit for measuring transceiver driver symmetry

13.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q100 Rev-H - Failure mechanism based stress test qualification for integrated circuits*, and is suitable for use in automotive applications.

14 Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

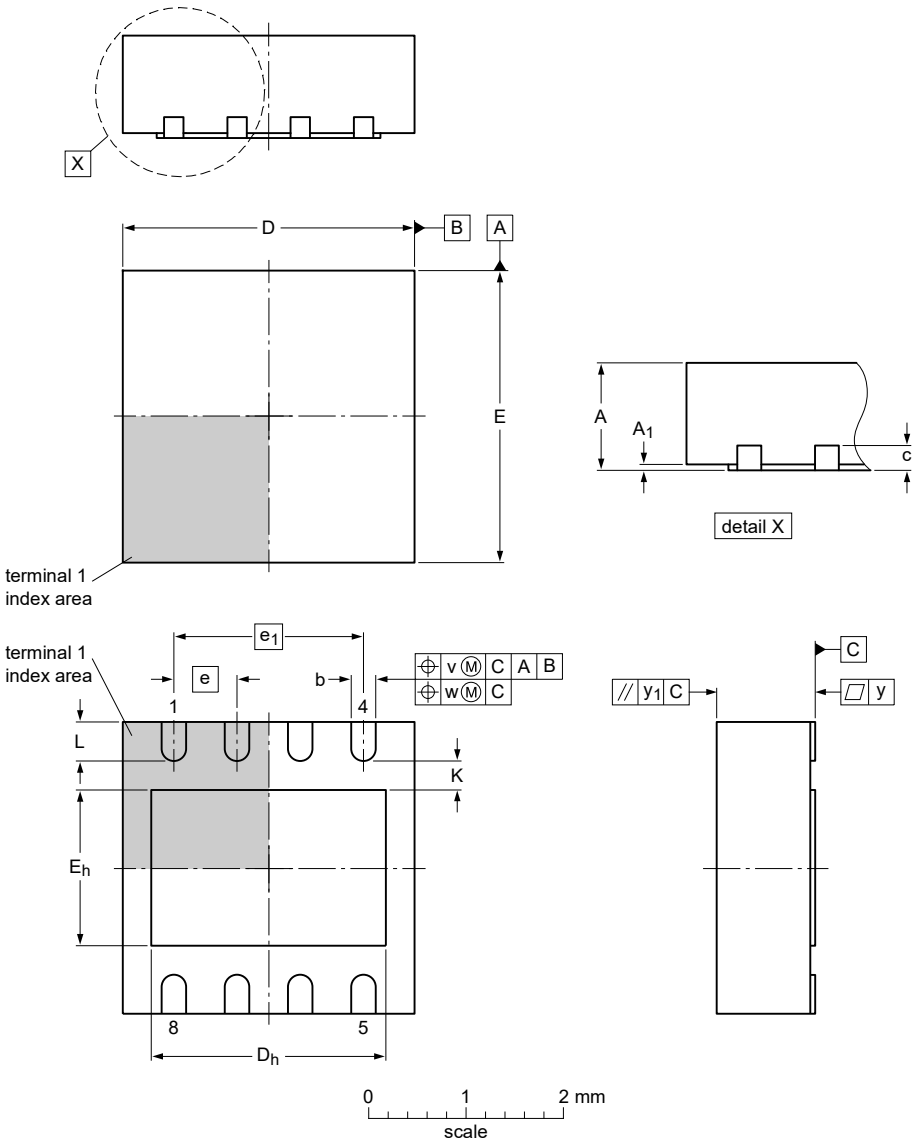
Notes

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				~~99-12-27~~ 03-02-18

Figure 14. Package outline SOT96-1 (SO8)

HVSON8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 x 3 x 0.85 mm **SOT782-1**



Dimensions

Unit(1)		A	A1	b	c	D	Dh	E	Eh	e	e1	K	L	v	w	y	y1
mm	max	1.00	0.05	0.35		3.10	2.45	3.10	1.65			0.35	0.45				
	nom	0.85	0.03	0.30	0.2	3.00	2.40	3.00	1.60	0.65	1.95	0.30	0.40	0.1	0.05	0.05	0.1
	min	0.80	0.00	0.25		2.90	2.35	2.90	1.55			0.25	0.35				

Note
1. Plastic or metal protrusions of 0.075 maximum per side are not included.

sot782-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT782-1	- - -	MO-229	- - -			~~09-08-25~~ 09-08-28

Figure 15. Package outline SOT782-1 (HVSON8)

15 Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

16 Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

16.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

16.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

16.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

16.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 16) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 10 and Table 11

Table 10. SnPb eutectic process (from J-STD-020D)

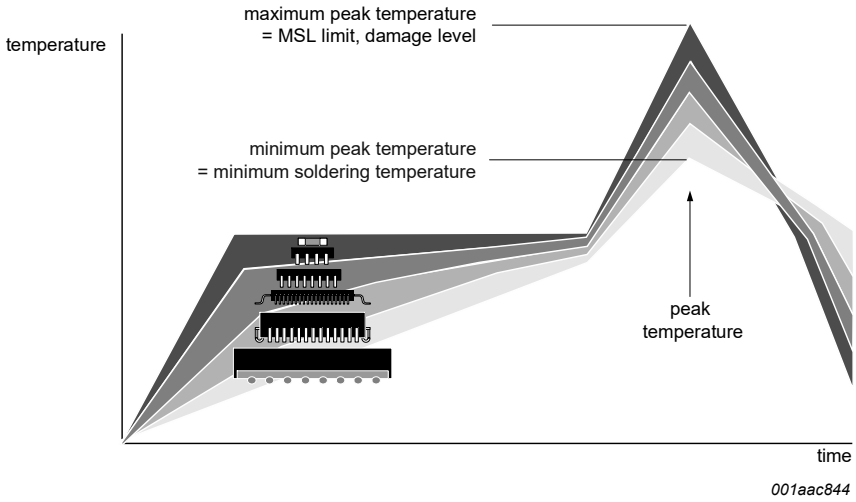
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 11. Lead-free process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 16.



MSL: Moisture Sensitivity Level

Figure 16. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

17 Appendix: ISO 11898-2:2024 parameter cross-reference lists

Table 12. ISO 11898-2:2024 to NXP data sheet parameter conversion[1]

ISO 11898-2:2024		NXP data sheet	
Parameter	**Notation**	**Symbol**	**Parameter**
HS-PMA maximum ratings of V_{CAN_H}, V_{CAN_L} and V_{Diff}			
Maximum rating	V_{Diff}	$V_{(CANH-CANL)}$	voltage between pin CANH and pin CANL
General maximum rating	V_{CAN_H} V_{CAN_L}	V_x	voltage on pin x
Optional: Extended maximum rating			
HS-PMA recessive output characteristics, bus biasing active/inactive			
Single ended output voltage on CAN_H	V_{CAN_H}	$V_{O(rec)}$	recessive output voltage
Single ended output voltage on CAN_L	V_{CAN_L}		
Differential output voltage	V_{Diff}	$V_{O(dif)}$	differential output voltage
HS-PMA dominant output characteristics			
Single ended voltage on CAN_H	V_{CAN_H}	$V_{O(dom)}$	dominant output voltage
Single ended voltage on CAN_L	V_{CAN_L}		
Differential voltage on normal bus load	V_{Diff}	$V_{O(dif)}$	differential output voltage
Differential voltage on effective resistance during arbitration			
Optional: Differential voltage on extended bus load range			
Maximum HS-PMA driver output current			
Absolute current on CAN_H	I_{CAN_H}	$I_{O(sc)}$	short-circuit output current
Absolute current on CAN_L	I_{CAN_L}		
HS-PMA static receiver input characteristics, bus biasing active/inactive			
Recessive state differential input voltage range Dominant state differential input voltage range	V_{Diff}	$V_{th(RX)dif}$	differential receiver threshold voltage
		$V_{rec(RX)}$	receiver recessive voltage
		$V_{dom(RX)}$	receiver dominant voltage
HS-PMA receiver input resistance (matching)			
Differential internal resistance	$R_{DIFF\_pas\_rec}$	$R_{i(dif)}$	differential input resistance
Single-ended internal resistance	$R_{SE\_pas\_rec\_H}$ $R_{SE\_pas\_rec\_L}$	R_i	input resistance
Matching of internal resistance	m_R	ΔR_i	input resistance deviation
HS-PMA maximum leakage currents on CAN_H and CAN_L, unpowered			
Leakage current on CAN_H, CAN_L	I_{CAN_H} I_{CAN_L}	I_L	leakage current
HS-PMA driver symmetry			
Driver symmetry	V_{sym_vcc}	V_{TXsym}	transmitter voltage symmetry
Optional HS-PMA transmit dominant time-out			
Transmit dominant time-out	t_{dom}	$t_{to(dom)TXD}$	TXD dominant time-out time

Table 12. ISO 11898-2:2024 to NXP data sheet parameter conversion[1]*...continued*

ISO 11898-2:2024		NXP data sheet	
Parameter	**Notation**	**Symbol**	**Parameter**
HS-PMA implementation loop delay requirements for parameter sets A, B and C			
Loop delay for parameter sets A and B	t_{Loop}	$t_{d(TXDH-RXDH)}$	delay time from TXD HIGH to RXD HIGH
Loop delay for parameter set C		$t_{d(TXDL-RXDL)}$	delay time from TXD LOW to RXD LOW
Propagation delay from TXD to CAN_H/CAN_L for parameter set C	$t_{prop(TXD\_BUS)}$	$t_{d(TXD-busdom)}$	delay time from TXD to bus dominant
		$t_{d(TXD-busrec)}$	delay time from TXD to bus recessive
Propagation delay from CAN_H/CAN_L to RXD for parameter set C	$t_{prop(BUS\_RXD)}$	$t_{d(busdom-RXD)}$	delay time from bus dominent to RXD
		$t_{d(busrec-RXD)}$	delay time from bus recessive to RXD
HS-PMA implementation data signal timing requirements for parameter sets A, B and C			
Transmitted recessive bit width variation	$t_{\Delta Bit(Bus)}$	$\Delta t_{bit(bus)}$	transmitted recessive bit width deviation
Received recessive bit width variation	$t_{\Delta Bit(RXD)}$	$\Delta t_{bit(RXD)}$	received recessive bit width deviation
Receiver timing symmetry	$t_{\Delta REC}$	Δt_{rec}	receiver timing symmetry
HS-PMA implementation SIC timing and impedance for parameter set C			
Differential internal resistance (CAN_H to CAN_L)	$R_{DIFF\_act\_rec}$	$R_{i(dif)actrec}$	active recessive phase differential input resistance
Internal single-ended resistance	$R_{SE\_act\_rec}$	$R_{i(actrec)}$	active recessive phase input resistance
Start time of active signal improvement phase	$t_{act\_rec\_start}$	$t_{d(TXD-busactrec)start}$	delay time from TXD to bus active recessive start
End time of active signal improvement phase	$t_{act\_rec\_end}$	$t_{d(TXD-busactrec)end}$	delay time from TXD to bus active recessive end
Start time of passive recessive phase	$t_{pas\_rec\_start}$	$t_{d(TXD-buspasrec)start}$	delay time from TXD to bus passive recessive start
PMA voltage wake-up control timing			
CAN activity filter time, long/short	t_{Filter}	$t_{wake(busdom)}$ $t_{wake(busrec)}$	bus dominant wake-up time bus recessive wake-up time
Wake-up time-out	t_{Wake}	$t_{to(wake)bus}$	bus wake-up time-out time
Wake-up pattern signaling	t_{Flag}	$t_{startup(RXD)}$	RXD start-up time
		$t_{startup(INH)}$	INH start-up time
		$t_{startup(ERR\_N)}$	ERR_N start-up time
Number of recessive bits before next SOF			
Number of recessive bits before a new SOF shall be accepted	n_{Bits_idle}	$N_{bit(idle)}$	number of idle bits before a SOF is accepted
BitFilter in CAN FD data phase			
CAN FD data phase bitfilter (option 1)	$\rho_{Bitfilter\_option1}$	$t_{fltr(bit)dom}$	dominant bit filter time
CAN FD data phase bitfilter (option 2)	$\rho_{Bitfilter\_option2}$		
HS-PMA bus biasing control timing			
Time-out for bus inactivity	$t_{Silence}$	$t_{to(silence)}$	bus silence time-out time
Bus bias reaction time	t_{Bias}	$t_{d(busact-bias)}$	bus bias reaction time

[1] A number of proprietary NXP parameters are equivalent to parameters defined in ISO 11898-2:2024, but use different symbols. This conversion table allows ISO parameters to be cross-referenced with their NXP counterparts. The NXP parameters are defined in the Static and Dynamic characteristics tables. The conversion table provides a comprehensive listing - individual devices may not include all parameters.

18 Appendix: TJx14(41/42/43/48)x, TJx14(62/63)x , TJF1441 family overview

Table 13. Feature overview of the complete TJx14(41/42/43/48)x, TJx14(62/63)x , TJF1441 family

	Modes				Supplies			Data rate		Additional features					
Device[1]	Normal	Standby	Sleep	Silent/Listen-only	VCC pin	VIO pin	VBAT pin	Up to 5 Mbit/s CAN FD	Up to 8 Mbit/s CAN FD[2]	Signal improvement[3]	Wake-up source recognition[4]	Short WUP support [0.5 - 1.8 µs][5]	Single supply pin wake-up[6]	TXD dominant time-out	Local diagnostics via ERR_N pin
TJx1441A	●			●	●	●		●						●	
TJx1441B	●			●	●			●						●	
TJx1441D	●			●	●			●						●	
TJF1441A	●			●	●	●		●						[7]	
TJx1442A	●	●			●	●		●				●	●	●	
TJx1442B	●	●			●			●				●		●	
TJx1443A	●	●	●	●	●	●	●	●			●	●	●	●	●
TJx1448A	●	●			●	●		●				●	●	●	
TJx1448B	●	●			●			●				●		●	
TJx1448C	●	●			●	●		●			●	●	●	●	
TJx1462A	●	●			●	●		●	●	●		●	●	●	
TJx1462B	●	●			●			●	●	●		●		●	
TJx1463A	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●

[1] TJx: TJA14xxx is AEC-Q100 Grade 1; TJR14xxx is AEC-Q100 Grade 0; TJF1441A is non-automotive grade.
[2] Only guaranteed for TJA1462x and TJA1463x, AEC-Q100 Grade 1.
[3] CAN FD signal improvement capability (SIC) according to ISO11898-2:2024 parameter set C.
[4] RXD is held LOW after wake-up request, enabling wake-up source recognition.
[5] WUP = wake-up pattern according to Figure 7 in ISO 11898-2:2024.
[6] Only VIO supply needed for wake-up in TJA1442A, TJA1448A, TJA1448C, TJA1462A; only VBAT supply needed for wake-up in TJA1443A, TJA1463A.
[7] Not having TXD dominant time-out allows for very low data rates in non-automotive grade applications.

19 Revision history

Table 14. Revision history

Document ID	Release date	Description
TJA1462 v.3.0	12 February 2025	• ISO 11898-2:2016 upgraded to ISO 11898-2:2024 throughout • Replaced CiA 601-4:2019 with ISO 11898-2:2024 parameter set C throughout • Section 2.1: 3rd list item revised (on bit timing symmetry) • Table 3: table title and table notes 2 and 4 amended • Section 7.1.2: text of 4th paragraph revised • Section 7.1.3: text of 1st paragraph revised • Section 7.2: text of 1st paragraph amended • Section 7.3.4: text deleted at end of paragraph • Section 7.3.5: text of last paragraph amended • Table 6: SAE J2962-2:2019 V_{ESD} entries added • Table 8: – measurement conditions amended: I_{CC}, $I_{O(sc)rec}$, R_i, ΔR_i, $R_{i(dif)}$ – values changed: $V_{rec(RX)}$ – parameters deleted: $R_{i(extdom)}$, $R_{i(dif)extdom}$ – table notes 7 and 8 (now 9) revised – table notes 8 and 10 added • Table 9: – formatting of CAN (FD) timing characteristics revised (including table notes) – parameter added: $t_{d(TXD\text{-}buspasrec)start}$ – parameter value changed: $t_{d(TXD\text{-}busactrec)end}$ (min) – parameters deleted: $t_{d(TXD\text{-}busrec)end}$, $t_{d(TXD\text{-}busdom)end}$, $t_{d(extbusdom)end}$ • Original Figs. 7 and 8 combined in new single Figure 8 • Figure 9 revised (absolute values and extended dominant phase removed) • Redundant original Fig. 11 removed • Original Section 17 deleted • Section 18: section title, table title and table notes 2, 3 and 5 amended • Section 17: cross-reference tables updated • Legal information: *HTML publications* disclaimer added
TJA1462 v.2.0	15 October 2021	-
TJA1462 v.1.0	12 August 2020	• Initial version

Legal information

Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL https://www.nxp.com.

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